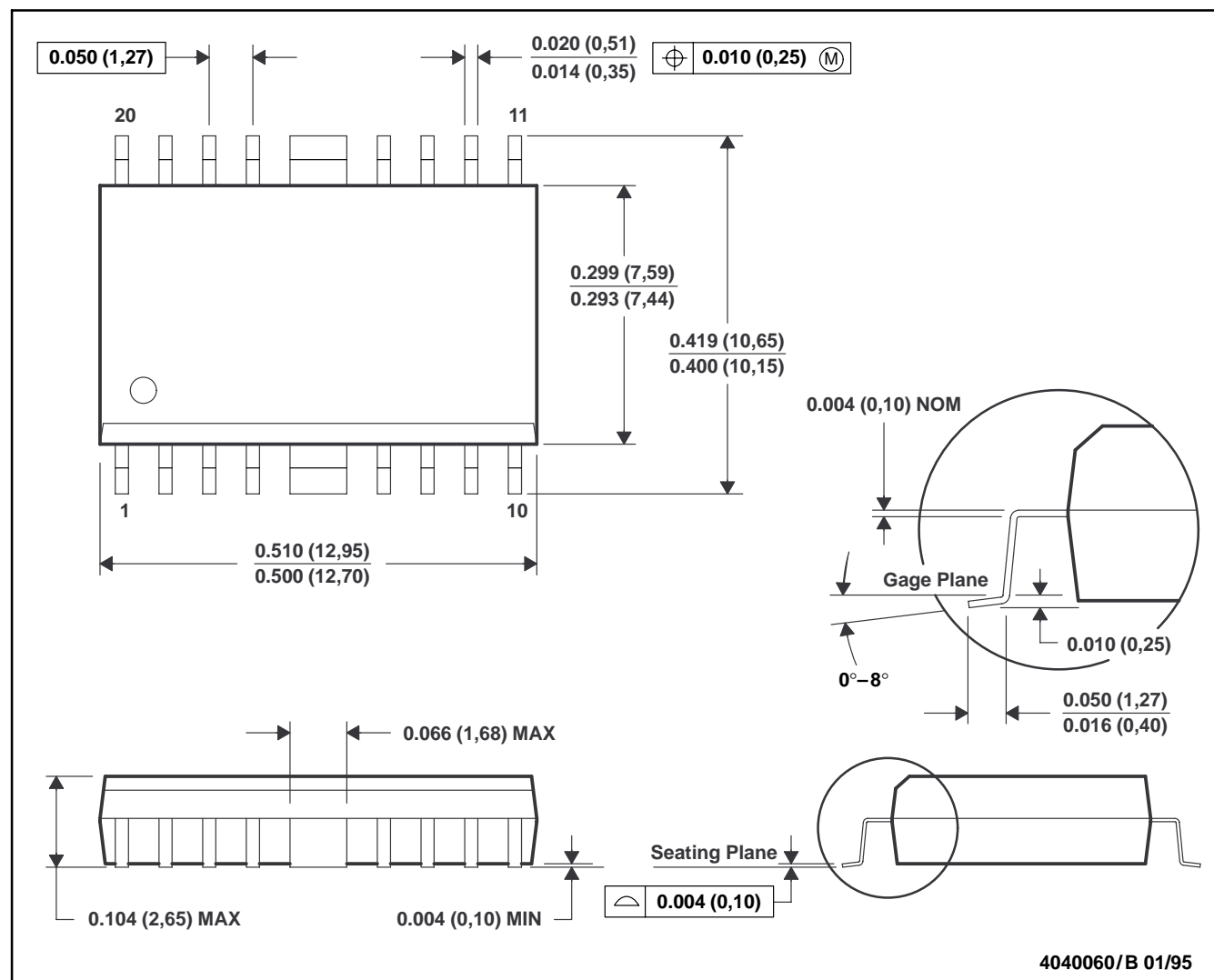


## DZA (R-PDSO-G20)

## PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions include mold flash or protrusion.
  - Thermally enhanced molded plastic package with tabbed leads connected to the die pad.

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